

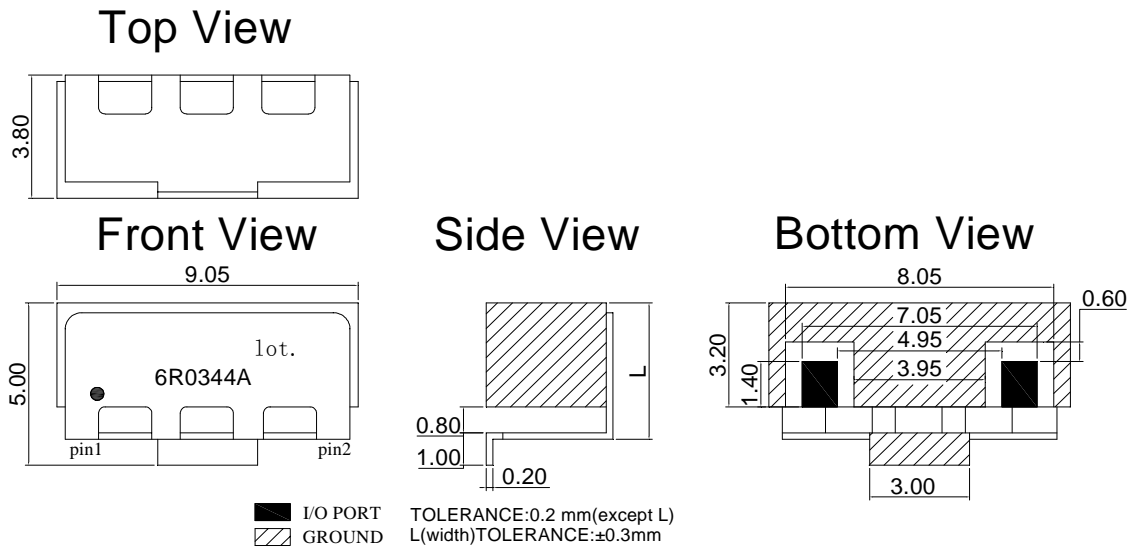
FEATURES

- Small Size,Light weight
- SMT package soldering
- Ideal for Microwave telecommunication

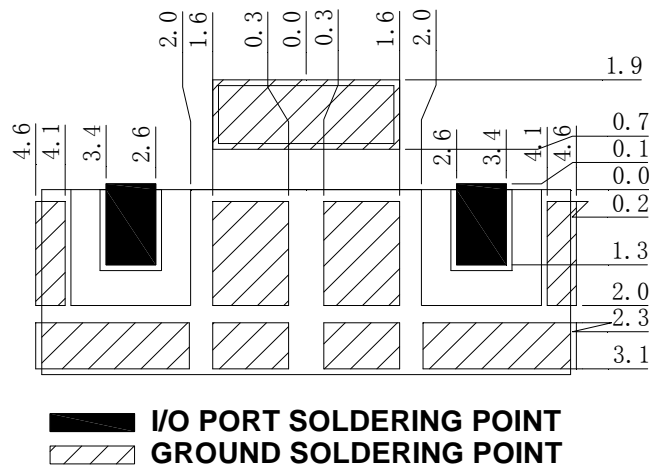
SPECIFICATIONS

| NO. | ITEM | Spec | | | UNIT | |
|-----|---------------------------------|---------------|--------|------|------|----|
| | | Min | Typ | Max | | |
| 1 | Center Frequency | 5170 | 5502.5 | 5835 | MHz | |
| 2 | Bandwidth [BW] | / | 665 | / | MHz | |
| 3 | Insertion Loss in BW | / | / | 2.8 | dB | |
| 4 | Ripple in BW | / | / | 2.3 | dB | |
| 5 | VSWR in BW | / | / | 2.0 | / | |
| 6 | Attenuation [Absolute Value] | @30~2500MHz | 35 | / | / | dB |
| | | @2512~3600MHz | 30 | / | / | |
| | | @3800~4200MHz | 30 | / | / | |
| | | @4800~4900MHz | 25 | / | / | |
| | | @5935~6200MHz | 50 | / | / | |
| | | @6200~7125MHz | 50 | / | / | |

OUTLINE DRAWING



FOOTPRINT



ABSOLUTE MAXIMUM RATINGS

| | |
|------------------------------|----------------|
| Operation Temperature | -40°C to +95°C |
| Storage Temperature | -40°C to +95°C |
| Max. Input Power | 33dBm |

NOTES

- RoHS 2.0/HSF
- Reflow soldering temperature curve

